Application No. 09/548,140

AMENDMENTS TO THE SPECIFICATION

In the Specification

Please substitute the following amended paragraph(s) and/or section(s) (deleted matter is shown by strikethrough and added matter is shown by underlining):

Page 2, line 6-line 13,

Heretofore, various methods have been proposed to bond an aluminum plate and a ceramic substrate board as shown in Japanese Unexamined Utility Model Publication No. 57945/1991 and Japanese Unexamined Utility Model Publication No. 68448/1990. Among these methods, an aluminum plate is bonded to an aluminum nitride board or an alumina board by using a brazing material of Al--Si series or Al--Ge series. U.S. Pat. No. 3,994,430, published [[on]] in 1976, shows the use of silicone as an aluminum binding assistant.

Page 21, line 22-page 22, line 8,

(4) ~~Cupper~~ Copper used conventionary as a base plate is cheap. However, the thermal expansion coefficient is larger than that of the ceramics, so that the reliability is low because a crack is formed easily on the bonding surface between the ceramic substrate board and the base plate when the heating and cooling are repeated. ~~Cupper~~ Copper molybdenum alloy or aluminum silicon carbide composite material is low in heat conductivity and high in cost. On the contrary, aluminum is cheap and very small in proof stress, though the thermal expansion cofficient is high, so that the crack is hardly formed on the boundary surface between the ceramic substrate board and the base plate even if the heating and cooling are repeated and that high reliability can be obtained.